

SE 1262

Flexible Epoxy Coating & Encapsulant

Typical Properties			
Property	Unit	Value	Test Method
Color of Component A		Brown	Visual
Color of Component B		Blue	Visual
Mixing Ratio	In wt. or vol.	1:1	
Density	Gram /cc	1.1	ASTM D792
Viscosity at 25°C	cps	1200	ASTM D2196
Property as Cured			
Color		Blue	Visual
Hardness	Shore A	32	ASTM D2240
Tensile Strength	Mpa	2.8	ASTM D638
Elongation	%	80	ASTM D638
Dielectric Constant	@1000Hz	4.0	ASTM D150
Dielectric Strength	Volt/mil AC	> 400	ASTM D149
Volume Resistivity (@24°C)	Ohm-cm	> 10E+13	ASTM D257
Coefficient of Thermal Expansion	ppm/°C	140	IPC-TM-650
Adhesion (Al/Al lap shear)	Psi	> 200	ASTM D1002
Temperature Usage	°C	-80 to 160	TGA
Cure Profile			
Cure at 125°C	min	45	Durometer
Cure at 150°C	min	30	Durometer
Pot / Work Life at 25°C (after mixing up)	hr	12	Viscosity double

These figures are only intended as a guide and should not be used in preparing specifications.

Processing Instruction

Only components A and B with the same lot number may be processed together! For potting applications, it is recommended to warm the part A to ~60°C, then mix with part B. Any possible air bubbles in mixing or potting process can be removed by vacuum.

We recommend running preliminary tests to optimize conditions for the particular application. Comprehensive processing instructions can be obtained by contacting directly to United Adhesives, Inc.

Storage

SE 1262 has a shelf life of at least 12 months when stored in the originally sealed containers. The 'Best use before end' date of each batch appears on the product label. Storage beyond the date specified on the label does not necessarily mean that the product is no longer usable. In this case however, the properties required for the intended use must be checked for quality assurance reasons.

Safety information

General hygiene regulations should be observed. Comprehensive instructions are given in the corresponding Material Safety Data Sheets. They are available on request from United Adhesives, Inc.

Characteristics

SE 1262 is a soft and flexible epoxy adhesive for under-filling or encapsulating electronic devices and components such as BGA, chip-on-board, bare die, CSP etc. It is a two-part, capillary flow formulation that cures at elevated temperature to form "rubber-like" soft epoxy that provides protection of electronics with significantly reduced thermal stress. SE 1262 is dispensable. For better flow, it is recommended to pre-warm the applied spot to ~ 105°C.

Special Features and Benefits

- Softness and flexibility for stress free
- Fast flow and capillary flow
- Bonding to various substrates
- Low bleeding, low volatile

Typical Applications

- Under-filling BGA, Bare die, flip-chip, CSP
- Encapsulate parts, cavities
- Bonding of die to LTCC, Al, Cu
- Attach PCBs, base plates, components
- Seal lids, covers, housings, connectors
- Vibration dampening
- Thermal stress coupling
- Aerospace & Automotive electronics
- Semiconductor & Telecommunications

SE 1262 has a shelf life of at least 12 months when stored at ambient condition (< 25°C) in the originally sealed containers.